Copy of ADI_PCN_16_0027_Rev_A_Material_Report.xlsx

ANALOG DEVICES

Analog Devices, Inc. PCN Material Report (Proprietary Information)

Existing Material		Material Added		Material Removed	
GENERICNUMBER	MATERIALNUMBER	GENERICNUMBER	MATERIALNUMBER	GENERICNUMBER	MATERIALNUMBER
		ADUCM320	ADUCM320BBCZ	ADDI9009	ADDI9009BBCZ
		ADUCM320	ADUCM320BBCZI	ADDI9009	ADDI9009BBCZRL

Copy of ADI_PCN_16_0027_Rev_A_Part List with BOM change.xlsx

FG_NAME	BodySize	PkgLeadCount	Wire Type(Before)	Wire Type(After)	Wire diameter(Before)	Wire diameter(After)	Epoxy(Before)	Epoxy(After)	Mold(Before)	Mold(After)	Terminal(Before)	Terminal(After)
ADAS1131JBCZ	15X15_MM	324	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	GE 100LFCS-GT	KE-G1280TS	SAC305	SAC305
ADAS1135JBCZ	15X15_MM	324	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	GE 100LFCS-GT	KE-G1280TS	SAC305	SAC305
ADUCM310BBCZ	6X6_MM	112	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM310BBCZ-RL	6X6_MM	112	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM320BBCZI-RL	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM320BBCZ-RL	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM322BBCZ	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM322BBCZI	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM322BBCZI-RL	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM322BBCZ-RL	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM320BBCZ	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305
ADUCM320BBCZI	6X6_MM	96	Gold	Gold	0.8	0.8	HR 9050G	HR 9070G	G770LC	G770LC	SAC305	SAC305

Assembly Site Transfer of Select CSP_BGA Products to STATS ChipPAC Korea

Qualification Plan Summary
for CSP_BGA and BOM Change at STATS ChipPAC Korea

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	September 2016
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 32	September 2016
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	September 2016
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	1 x 32	September 2016

*Preconditioned per JEDEC/IPC J-STD-020